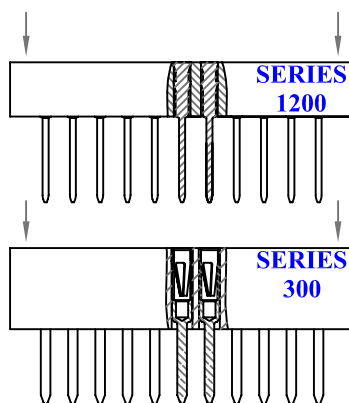
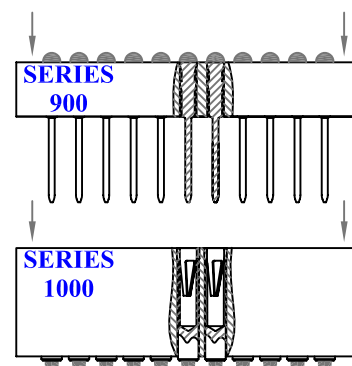


for

**.0315 [.80 MM] ADAPTERS**

**.8MM BGA DEVICE**

OR

**.8MM LGA DEVICE**

**THRU-HOLE**

**SURFACE MOUNT**
**Thermal Performance (STANDARD FR-4):**

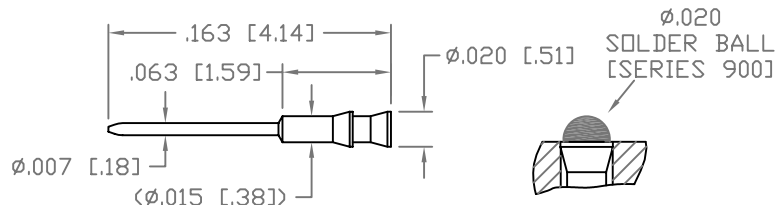
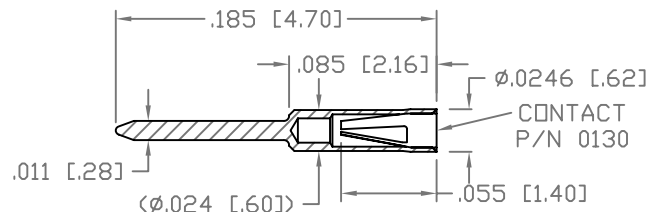
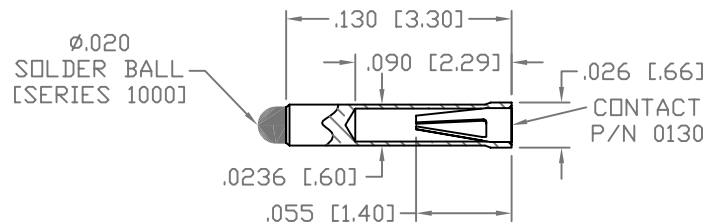
Operating Temperature [range] (To):	-55° to 140° C
Glass Transition Temperature [range] (Tg):	150° to 200° C
Resistance to Soldering Heat [Thermal Stress]:	10 seconds @ 288° C
Flammability rating:	UL94V-0
IEC Climatic Category:	55 / 125 / 21

**Electrical Performance: Tests IAW MIL-STD-202 OR -1344 Methods.**

Maximum Voltage:	50VAC/60VDC
Maximum Current:	1 Amperes per contact
Contact Resistance: Dry Circuit:	10 milliohms Max. @ 10 ma / 5VDC
Insulation Resistance, @500VDC:	5,000 MegOhms Min.
Dielectric Withstanding Voltage:	500VAC Min.
Capacitance:	1 pf (PicoFarads) Max.
Self Inductance:	2 nH (NanoHenries) Max.

**Contact Materials & Finishes (Other finishes available):**

Bodies:	Brass Alloy C36000 per ASTM-B16, 1/2 Hard. Plated 10 uIn. Min. Gold over 50uIn Min. Nickel [0r] 100 uIn. Min. Tin over 50 uIn. Min. Nickel.
Clips:	Beryllium Copper Alloy C17200 per ASTM-B194 Plated 10uIn Min. Gold over 50uIn Min. Nickel
Solder Balls:	63/37 [Sn/Pb] Eutectic Solder, Ø.020 Melting Temperature 183°C[361°F]


**P/N 0108**

**P/N 0114**

**P/N 0116**
**PART NUMBER / ORDER INFORMATION:**
**1000 - 121 F - 0116 - 11A4**

PRODUCT CODE

PIN COUNT

MATERIAL

CONTACT P/N

PATTERN CODE

300 = SOCKET, PIN GRID ARRAY [PGA]

A = ACRYLIC

900 = LGA INTERPOSER [PGA]

E = PEEK [POLYETHERETHERKETONE]

1000 = SOCKET, BGA [SBGA]

H = POLYIMIDE, [MIL-L-13949/10]

1200 = BGA INTERPOSER [PBGA]

F = FR-4, [IPC-4101/24]

R = RYTON [POLYPHENYLENE SULFIDE]

U = G.E. ULTEM [POLYETHERIMIDE]

**01A1 - 99Z9**
**OVER 24,000  
PATTERNS  
AVAILABLE**